

PCN# : P314A
Issue Date : Apr. 16, 2013

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Jul. 15, 2013

Expected First Date Code of Changed Product :1319

Description of Change (From) :

Products assembled in the SOD323F using the BOM as below.

PROCESS OF RECORDS	FROM
Leadframe Materials	C194R-H
Wire	Au
Mold compound	ELER-8-500C
Die Top metal thickness	1.3um

Description of Change (To) :

Products assembled in the SOD323F using the new BOM as below.

PROCESS OF RECORDS	TO
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Leadframe Materials	Alloy 42
Wire	Cu
Mold compound	ELER-8-500C/ SG-8300CS
Die Top metal thickness	3um

Reason for Change:

New materials set qualification. These changes will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will be fully compliant to all published data sheet specifications. Quality and reliability will remain at the highest standards already demonstrated with Fairchild's existing products.

Affected Product(s):

1N4148WS	1N4448WS	1N914BWS
MM3Z10VB	MM3Z10VC	MM3Z11VB
MM3Z11VC	MM3Z12VB	MM3Z12VC
MM3Z13VB	MM3Z13VC	MM3Z15VB
MM3Z15VC	MM3Z16VB	MM3Z16VC
MM3Z18VB	MM3Z18VC	MM3Z20VB
MM3Z20VC	MM3Z22VB	MM3Z22VC
MM3Z24VB	MM3Z24VC	MM3Z27VB
MM3Z27VC	MM3Z2V4B	MM3Z2V4C
MM3Z2V7B	MM3Z2V7C	MM3Z30VB
MM3Z30VC	MM3Z33VB	MM3Z33VC
MM3Z36VB	MM3Z36VC	MM3Z39VB
MM3Z39VC	MM3Z3V0B	MM3Z3V0C
MM3Z3V3B	MM3Z3V3C	MM3Z3V6B
MM3Z3V6C	MM3Z3V9B	MM3Z3V9C
MM3Z43VB	MM3Z43VC	MM3Z47VB
MM3Z47VC	MM3Z4V3B	MM3Z4V3C
MM3Z4V7B	MM3Z4V7C	MM3Z51VB
MM3Z51VC	MM3Z56VB	MM3Z56VC
MM3Z5V1B	MM3Z5V1C	MM3Z5V6B
MM3Z5V6C	MM3Z62VB	MM3Z62VC
MM3Z68VB	MM3Z68VC	MM3Z6V2B
MM3Z6V2C	MM3Z6V8B	MM3Z6V8C
MM3Z75VB	MM3Z75VC	MM3Z7V5B
MM3Z7V5C	MM3Z8V2B	MM3Z8V2C
MM3Z9V1B	MM3Z9V1C	

Qualification Plan	Device	Package	Process	No. of Lots
Q20130082	MM3Z75VC	SOD323F	Zener	2

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	JESD22-A113		0/308
Temperature Cycle	-65C, 150C	JESD22-A104	500 cycles	0/154
Power Cycle	Delta 100 C, 2 Min cycle	MIL-STD-750-1036	10000 cycles	0/154
High Temperature Reverse Bias Test	150C, 80% of BV	JESD22-A108	1000 hrs	0/77
Temperature Humidity Bias Test	85C, 85%RH, 80% BV	JESD22-A101B	1000 hrs	0/154
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/154

Qualification Plan	Device	Package	Process	No. of Lots
Q20130082	1N4148WS	SOD323F	Switching	2

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260C	JESD22-A113		0/308
Temperature Cycle	-65C, 150C	JESD22-A104	500 cycles	0/154
Power Cycle	Delta 100 C, 2 Min cycle	MIL-STD-750-1036	10000 cycles	0/154
High Temperature Reverse Bias Test	150C, 80% of BV	JESD22-A108	1000 hrs	0/77
Temperature Humidity Bias Test	85C, 85%RH, 80% BV	JESD22-A101B	1000 hrs	0/154
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/154